

Not recommended for new applications. Please see 0679L

# Type SSQ

## Square Ceramic Surface Mount Quick Acting Fuse

HF  SSQ Series – 2410 Size

RoHS 2 Compliant

### Features

- Quick Acting
- Small size, 2410 SMD
- Wide range of current rating from 100mA to 15A
- Wide operating temperature range
- Tape & Reel for auto-insert SMD process
- Compatible with 260°C, IR Pb-free solder process
- RoHS 2 compliant (MSL = 1)
- Halogen Free
- Lead Free

### Applications

- Notebook
- LCD monitor
- PC computer
- Office electronic equipment
- Industrial equipment
- Medical equipment
- POE, POE+
- LCD / LED monitor
- Power supply
- LCD / LED TV



LEAD FREE =   
 HALOGEN FREE = 

### Electrical Characteristics (UL/CSA/STD.248-14)

Testing Current	Blow Time	
	Minimum	Maximum
100%	4 Hrs.	N/A
200%	N/A	5 Sec

### Safety Agency Approvals

Safety Agency	Safety Agency Certificate	Voltage Rating (V)	Ampere Range / Volt @ I.R. ability*
	LR39772		100mA-7A/125V @50A AC
	E20624	100mA-7A/125V AC 125V DC 7.1A-12A/125V AC 86V DC 15A/86V DC	100mA-7A/125V @ 50A AC 86V @ 10kA DC 125V @ 300A DC 7.1A-12A/125V @ 50A AC 86V @ 10kA DC
	E20624		15A/86V @ 10kA DC

\*I.R.= Interrupting Rating = Short Circuit Rating(Amps)

### Physical Specifications

Materials	Body : Ceramic
	Terminations : Palladium plated Brass Caps
Marking	On Fuse :
	"Current Rating" in black color, "bel" stamped in end caps.
	On Label :
	"bel", "SSQ", "Current Rating", "Voltage Rating", "Interrupting Rating", "Appropriate Safety Logos" and "  ", "  " (China RoHS compliant).

## Temperature Derating Curve



## Average Time Current Curve



## Electrical Specifications

Catalog Number	Ampere Rating	Typical Cold Resistance (ohms)	Volt-drop @100% In (Volt) max.	Voltage and Interrupting Ratings	Melting I <sup>2</sup> T <10 m Sec (A <sup>2</sup> Sec)	Melting I <sup>2</sup> T @10 In (A <sup>2</sup> Sec)	Maximum Power Dissipation (W)	Agency Approvals		
								UL US	SP	RA US
SSQ 250	250mA	0.560	0.30	See Table of Safety Approvals on Page 1 for Voltage and associated Interrupting Ratings	0.02	0.01	0.07	Y	Y	
SSQ 375	375mA	0.335	0.27		0.04	0.03	0.09	Y	Y	
SSQ 500	500mA	0.235	0.26		0.07	0.06	0.11	Y	Y	
SSQ 750	750mA	0.131	0.19		0.11	0.07	0.13	Y	Y	
SSQ 1	1A	0.081	0.14		0.19	0.14	0.17	Y	Y	
SSQ 1.25	1.25A	0.065	0.14		0.33	0.24	0.20	Y	Y	
SSQ 1.5	1.5A	0.056	0.14		0.57	0.41	0.23	Y	Y	
SSQ 2	2A	0.039	0.13		1.0	0.8	0.30	Y	Y	
SSQ 2.5	2.5A	0.031	0.13		1.7	1.4	0.36	Y	Y	
SSQ 3	3A	0.025	0.13		3.0	2.4	0.43	Y	Y	
SSQ 3.5	3.5A	0.024	0.13		3.9	3.3	0.47	Y	Y	
SSQ 4	4A	0.019	0.13		5.1	4.4	0.51	Y	Y	
SSQ 5	5A	0.013	0.12		8.8	7.8	0.62	Y	Y	
SSQ 6.3	6.3A	0.011	0.12		15	14	0.74	Y	Y	
SSQ 7	7A	0.009	0.110		20	19	0.81	Y	Y	
SSQ 8	8A	0.008	0.110		26	25	0.89	Y		
SSQ 10	10A	0.007	0.110		46	44	1.07	Y		
SSQ 12	12A	0.005	0.100		70	69	1.24	Y		
SSQ 15	15A	0.004	0.100	121	124	1.54			Y	

Consult manufacturer for other ratings



Specifications subject to change without notice

Bel Fuse Inc.  
206 Van Vorst Street  
Jersey City, NJ 07302 USA

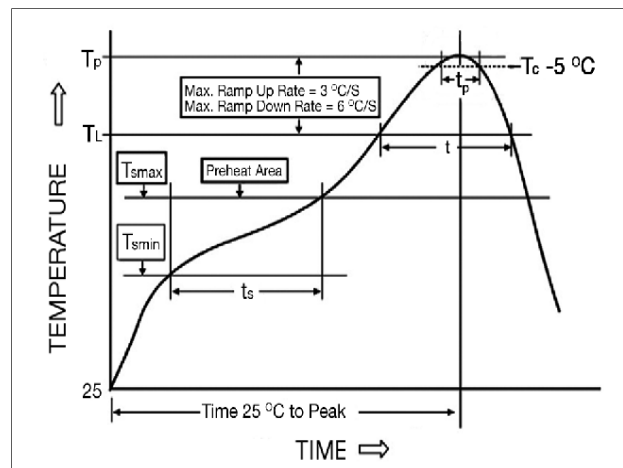
+1 201.432.0463  
Bel.US.CS@belf.com  
[belfuse.com/circuit-protection](http://belfuse.com/circuit-protection)

## Environmental Specifications

Shock Resistance	MIL-STD-202G, Method 213B, Test Condition 1 (100 G's peak for 6 milliseconds; Sawtooth waveform)
Vibration Resistance	MIL-STD-202G, Method 201A (10-55 Hz, 0.06 inch, total excursion).
Salt Spray Resistance	MIL-STD-202G, Method 101E, Test Condition B (48 hrs).
Insulation Resistance	MIL-STD-202G, Method 302, Test Condition A (After Opening) 10,000 ohms minimum.
Solderability	MIL-STD-202G, Method 208H
Resistance to solder Heat	MIL-STD-202G, Method 210F, Test Condition C. Top Side (260°C, 20 sec) MIL-STD-202G, Method 210F, Test Condition D. Bottom Side (260°C, 10 sec)
Thermal Shock	MIL-STD-202G, Method 107G, Test Condition B (-65°C to +125°C).
Operating Temperature	-55°C to +125°C
Moisture Sensitivity Level	1 ( According to IPC J-Std-020)

## Soldering Parameters

IR Reflow Profile (IPC/JEDEC J-STD-020D)	
<b>Preheat &amp; Soak</b>	
Temperature min (T <sub>sm</sub> )	150°C
Temperature max (T <sub>sm</sub> )	200°C
Time (T <sub>sm</sub> to T <sub>sm</sub> ) (ts)	60-120 seconds
Average ramp-up rate (T <sub>sm</sub> to T <sub>p</sub> )	3°C/second max.
Liquidous temperature (TL)	217°C
Time at liquidous (tL)	60-150 seconds
Peak temperature (T <sub>p</sub> )	260°C max
Time (tp) within 5°C of the specified classification temperature (T <sub>c</sub> )	30 seconds
Average ramp-down rate (T <sub>p</sub> to T <sub>sm</sub> )	6°C/second max.
Time 25°C to peak temperature	8 minutes max.



Lead-free Wave Soldering Profile	
Wave Soldering Parameter	
Average ramp-up rate	200°C / second
Heating rate during preheat	typical 1 - 2°C / second Max 4°C / second
Final preheat temperature	within 125°C of soldering temperature
Peak temperature T <sub>p</sub>	260°C
Time within +0°C / -5°C of actual peak temperature	10 seconds
Ramp-down rate	5°C / second max.

